

ON Semiconductor®

FDB9403-F085

N-Channel Power Trench® MOSFET **40V**, **110A**, **1.2m**Ω

Features

- Typ $r_{DS(on)}$ = 1m Ω at V_{GS} = 10V, I_D = 80A
- Typ $Q_{q(tot)}$ = 164nC at V_{GS} = 10V, I_D = 80A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Steering
- Integrated Starter/alternator
- Distributed Power Architectures and VRM
- Primary Switch for 12V Systems





MOSFET Maximum Ratings T_J = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain to Source Voltage		40	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current - Continuous (V_{GS} =10) (Note 1) T_C = 25°C		110	А
ID	Pulsed Drain Current	T _C = 25°C	See Figure4	^
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	968	mJ
D	Power Dissipation		333	W
P_D	Derate above 25°C		2.22	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance Junction to Case		0.45	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient	(Note 3)	43	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB9403	FDB9403-F085	TO-263AB	330mm	24mm	800 units

- Current is limited by bondwire configuration. Please see ON Semiconductor AN 9757-1 for details on test method.
 Starting T_J = 25°C, L = 0.47mH, I_{AS} = 64A, V_{DD} = 40V during inductor charging and V_{DD} = 0V during time in avalanche.
 R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Units

Max

Тур

Electrical Characteristics	$T_J = 25^{\circ}C$ unless otherwise noted
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Parameter

Off Ch	aracteristics						
B _{VDSS}	Drain to Source Breakdown Voltage	I _D = 250μA, \	/ _{GS} = 0V	40	-	-	V
1	Drain to Source Leakage Current	V _{DS} =40V,	$T_J = 25^{\circ}C$	-	-	1	μΑ
DSS	Drain to Source Leakage Current	$V_{GS} = 0V$	$T_J = 175^{\circ}C(Note 4)$	-	-	1	mA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

Test Conditions

Min

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250uA$		2.0	3.13	4.0	V
r _{DS(on)}	IDrain to Source On Resistance	I _D = 80A,	$T_{J} = 25^{\circ}C$	-	1.0	1.2	$m\Omega$
		V _{GS} = 10V	$T_J = 175^{\circ}C(Note 4)$	-	1.63	1.96	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1MHz		-	12700	-	pF
C _{oss}	Output Capacitance			-	3195	-	pF
C _{rss}	Reverse Transfer Capacitance			-	493	-	pF
R_g	Gate Resistance	f = 1MHz		-	2.9	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V _{GS} = 0 to 10V	V _{DD} = 20V	-	164	213	nC
Q _{g(th)}	Threshold Gate Charge	$V_{GS} = 0$ to 2V	I _D = 80A	-	23	30	nC
Q_{gs}	Gate to Source Gate Charge		_	-	59	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	25	-	nC

Switching Characteristics

t _{on}	Turn-On Time		-	-	56	ns
t _{d(on)}	Turn-On Delay Time		-	16	-	ns
t _r	Rise Time	$V_{DD} = 20V, I_D = 80A,$ $V_{GS} = 10V, R_{GS} = 1.5\Omega$	-	19.5	-	ns
t _{d(off)}	Turn-Off Delay Time		-	61	-	ns
t _f	Fall Time		-	46	-	ns
t _{off}	Turn-Off Time		-	-	171	ns

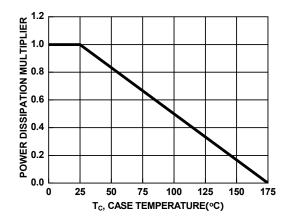
Drain-Source Diode Characteristics

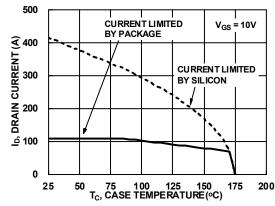
V_{SD}	Course to Ducin Diede Malters	$I_{SD} = 35A, V_{GS} = 0V$	-	-	0.85	V
	Source to Drain Diode Voltage	$I_{SD} = 15A, V_{GS} = 0V$	-	-	0.80	V
T _{rr}	Reverse Recovery Time	$I_{F} = 80A$, $dI_{SD}/dt = 100A/\mu s$	-	96	125	ns
Q _{rr}	Reverse Recovery Charge		-	149	194	nC

Notes

4: The maximum value is specified by design at TJ = 175°C. Product is not tested to this condition in production.

Typical Characteristics





NOTE: Refer to ON Semiconductor Application Notes AN9757

Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature

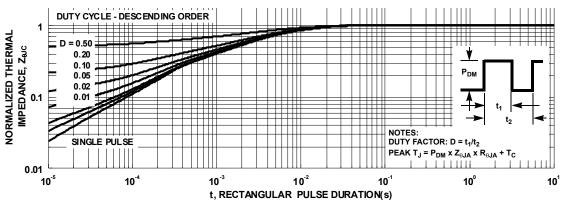


Figure 3. Normalized Maximum Transient Thermal Impedance

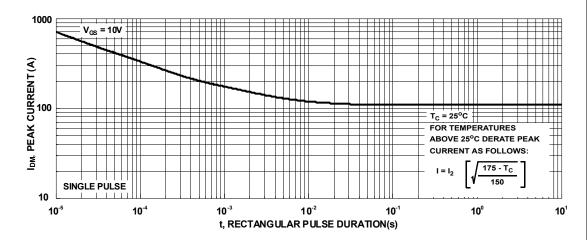


Figure 4. Peak Current Capability

Typical Characteristics

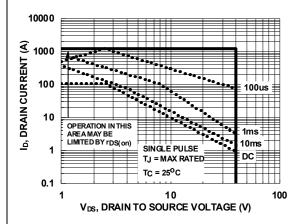


Figure 5. Forward Bias Safe Operating Area

NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

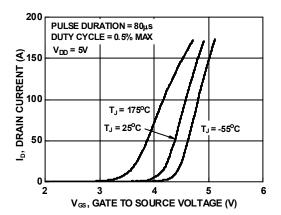


Figure 6. Unclamped Inductive Switching Capability

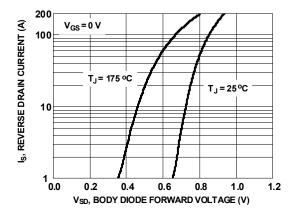
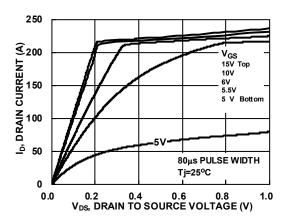


Figure 7. Transfer Characteristics

Figure 8. Forward Diode Characteristics



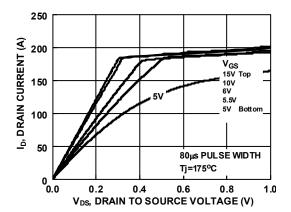


Figure 9. Saturation Characteristics

Figure 10. Saturation Characteristics

200

 $I_D = 80A$

V_{GS} = 10V

Typical Characteristics

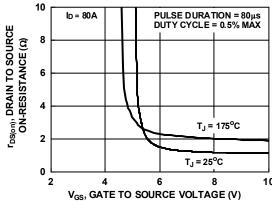
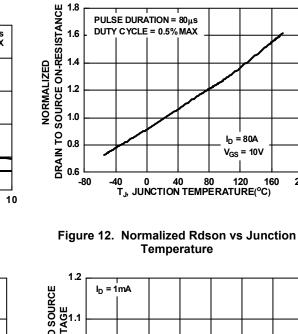


Figure 11. Rdson vs Gate Voltage



NORMALIZED

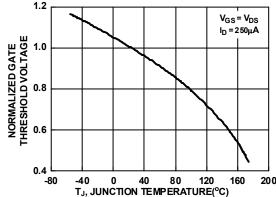
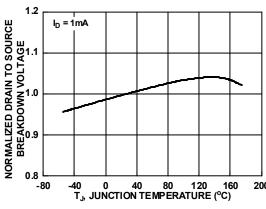


Figure 13. Normalized Gate Threshold Voltage vs **Temperature**



PULSE DURATION = 80μs

DUTY CYCLE = 0.5% MAX

Figure 14. Normalized Drain to Source **Breakdown Voltage vs Junction Temperature**

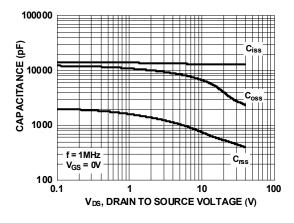


Figure 15. Capacitance vs Drain to Source Voltage

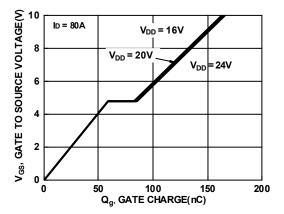


Figure 16. Gate Charge vs Gate to Source Voltage

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